

# The evolution of TDK 45nm Clean Technology

All-out, full on clean performance Reliable, Dependable Design

A large, dark circular graphic containing the product name in white text. The background of the entire advertisement features a dynamic, abstract design with blue and purple light streaks and a glowing central point.

**FOUP  
Load Port  
TAS300  
Type-E4**



# FOUP Load Port TAS300 Type-4

## 1. The highest degree of cleanness ever achieved in the industry

The number of microscopic particles reduced to the absolute minimum. The world's highest ever recorded level in a PWP test

- Designed to keep a unit thoroughly clean – the wiring and piping do not come into contact whilst the equipment is in operation.
- TDK's unique precision control air flow

## 2. High compatibility – compatible with the FOUP of every company

A unique mechanism, highly adaptable to the smallest difference in each FOUP, prevents any impact between the FOUP and the load port; secure and reliable latch key insertion gives high compatibility.

- Air cushion system: ensures secure and reliable attachment and removal, opening and closing with the FOUP of each company.
- Introduction result: world share No.1\* \* Since the start of sales in 2001, over 10,000 units sold (as of November 2005)

## 3. Improvements to maintenance

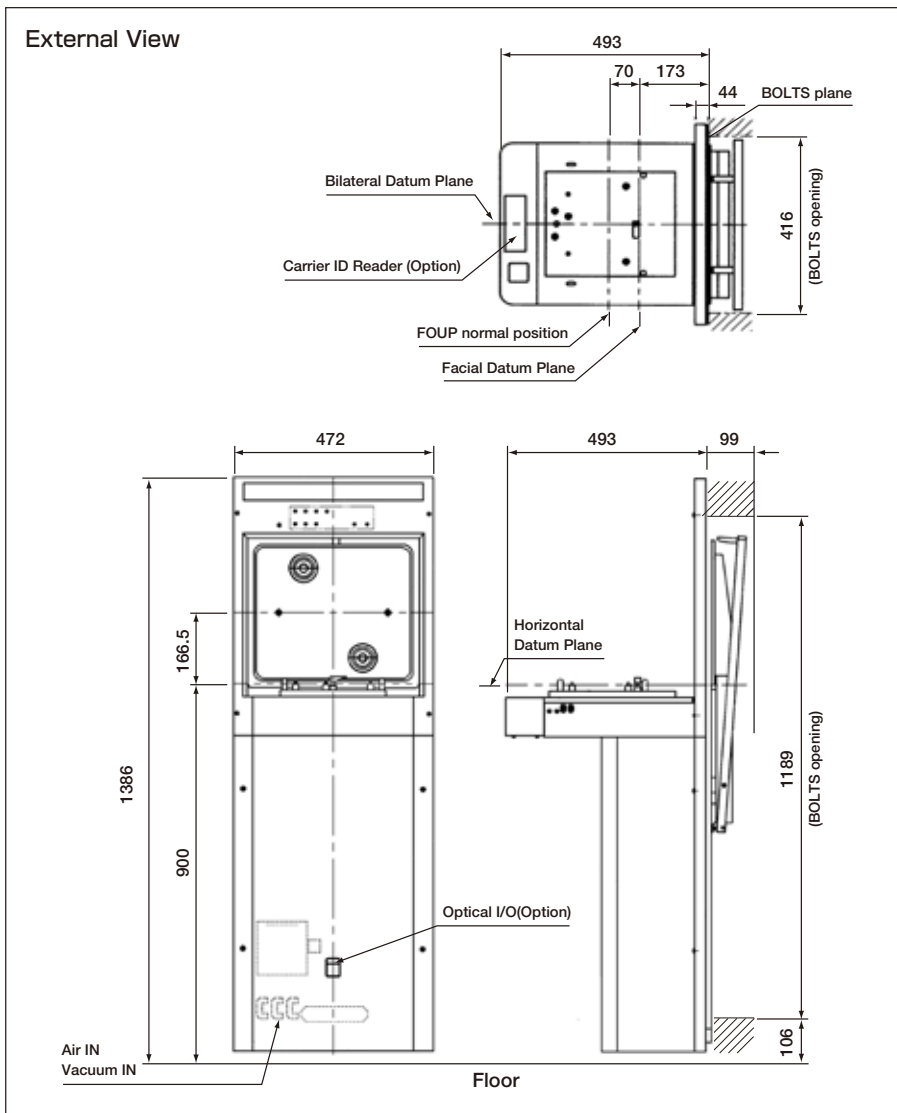
Designed for easy maintenance: maintenance in the minimum of time; the unit can without difficulty be quickly customized for any semiconductor production line.

- 50% time saving over earlier version: installation time into semiconductor manufacturing equipment and time for regular maintenance, including parts replacement slashed by more than half.

## 4. High reliability and high durability

TDK's factory automation technology ensures excellent reliability, stability and durability.

- A highly reliable design; outstanding results in reliability tests, decrease in the number of drive shafts.
- MCBF\* 500,000 times achieved \*MCBF – Mean Cycle Between Failure: the number of operations of a piece of equipment from the start of use or after repair of a malfunction, until the next equipment failure



### SPECIFICATIONS

#### Machine Capacity

Presence of FOUP

FOUP normal of position

#### Detection Function

Prevents hand front being caught

FOUP docking

Wafer flying out

FOUP Door detection

#### Stroke

Y-axis(FOUP forward and back motion)

70mm(SEMI Standard)

#### Repeat accuracy

Y-axis(FOUP forward and back motion)

±0.1mm

#### Operation time

FOUP open operation;10sec.

FOUP close operation;10sec.

#### Suitable Product Specifications

300mm FOUP(SEMI E47.1,E62 compliant product)

#### Options

Front Purge

#### N2 Purge

Bottom Purge

Details available on request.

Hybrid Purge



Read the operation manual and precautions thoroughly for safety handling before actually using it.



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